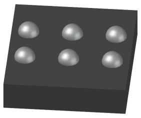
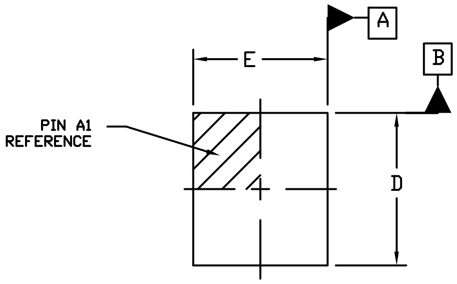
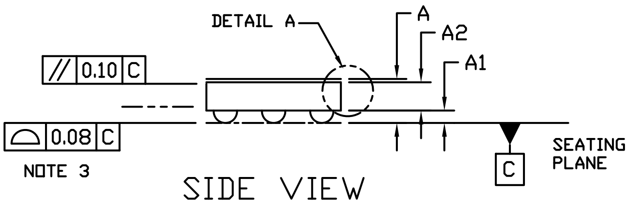


WLCSP6 1.11x0.98x0.35
CASE 567ZZ
ISSUE O

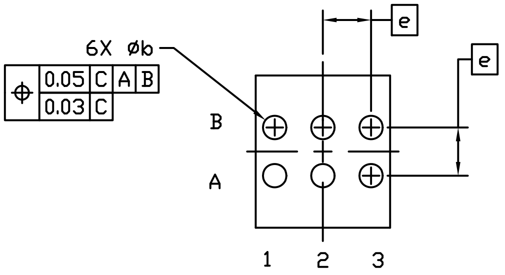
DATE 09 NOV 2021



TOP VIEW



SIDE VIEW

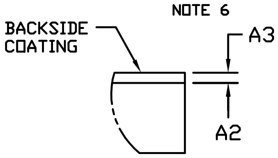


BOTTOM VIEW

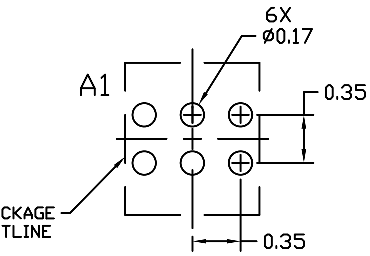
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	0.35
A1	0.080	0.100
A2	0.205 REF	
A3	0.025 REF	
b	0.15	0.19
D	1.091	1.121
E	0.961	0.991
e	0.35 BSC	

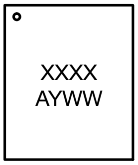


DETAIL A



RECOMMENDED
MOUNTING FOOTPRINT

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**WLCSP6 1.11x0.98x0.35**		**PAGE 1 OF 1**